

LPKF Launches Entirely New Flex Drilling & Cutting Laser

Contact:

Malte Borges
malte.borges@lpkf.com
Tel. +49 (0)5131 7095-1327
Fax +49 (0)5131 7095-90

LPKF Laser & Electronics AG

Osteriede 7
D-30827 Garbsen
www.lpkf.de

Board of Managing Directors

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Electronics manufacturing equipment manufacturer and laser specialist LPKF Laser & Electronics AG is launching an entirely new laser drilling and cutting system specifically tailored to the needs of the flexible circuit industry. The LPKF MicroLine 5000 is a UV laser based flex drilling system with a large working area of 21" x 24" and is available in two different laser power classes, depending on customer needs for various substrates and thicknesses. The system is equipped with precise process monitoring systems as well as intelligent vision systems for fiducial recognition and alignment.

Nils Heininger, Senior Vice President at LPKF explains, "We believed that the flex drilling market was underserved with the solutions currently existing in the marketplace in terms of speed, quality and cost. With LPKF being a specialist in laser based circuit processing, we felt we can do better and serve the industry with a modern laser system that is very fast and delivers superior quality drill holes at a very low cost of ownership." Although the system is mainly focused on high-speed drilling of both blind vias and through holes, it is equally effective for contour cutting of flexible circuits. With a small laser beam spot size of only 20 µm, it allows for precise cuts of intricate flex circuit geometries. The laser system is operating in the UV wavelength allowing it to drill and cut delicate substrate materials with a minimal heat affected zone. For added flexibility, LPKF's MicroLine 5000 can also be configured for reel-to-reel handling of flex substrates.

The company will demonstrate the LPKF MicroLine 5000 system from March 15th through 17th, 2016 for the Asian FPC market at Laser World of Photonics (booth #W5.5366), at the Shanghai New International Expo Centre and in North America at IPC APEX EXPO 2016 (booth #228), at the Las Vegas Convention Center.

About LPKF

LPKF Laser & Electronics AG manufactures machines and laser systems used in electronics fabrication, medical technology, the automotive sector, and the production of solar cells. Around 20 percent of the workforce is

engaged in research and development.